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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Active
Core Processor	M8C
Core Size	8-Bit
Speed	24MHz
Connectivity	I <sup>2</sup> C, SPI, UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	16
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 5.25V
Data Converters	A/D 28x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	<a href="https://www.e-xfl.com/product-detail/infineon-technologies/cy8c21334-24pvxit">https://www.e-xfl.com/product-detail/infineon-technologies/cy8c21334-24pvxit</a>

## PSoC Functional Overview

The PSoC family consists of many devices with on-chip controllers. These devices are designed to replace multiple traditional MCU-based system components with one low-cost single-chip programmable component. A PSoC device includes configurable blocks of analog and digital logic, and programmable interconnect. This architecture makes it possible for you to create customized peripheral configurations, to match the requirements of each individual application. Additionally, a fast central processing unit (CPU), flash program memory, SRAM data memory, and configurable I/O are included in a range of convenient pinouts.

The PSoC architecture, shown in [Figure 2](#), consists of four main areas: the core, the system resources, the digital system, and the analog system. Configurable global bus resources allow combining all of the device resources into a complete custom system. Each CY8C21x34 PSoC device includes four digital blocks and four analog blocks. Depending on the PSoC package, up to 28 GPIOs are also included. The GPIOs provide access to the global digital and analog interconnects.

### The PSoC Core

The PSoC core is a powerful engine that supports a rich instruction set. It encompasses SRAM for data storage, an interrupt controller, sleep and watchdog timers, and internal main oscillator (IMO) and internal low speed oscillator (ILO). The CPU core, called the M8C, is a powerful processor with speeds up to 24 MHz <sup>[3]</sup>. The M8C is a four-million instructions per second (MIPS) 8-bit Harvard-architecture microprocessor.

System resources provide these additional capabilities:

- Digital clocks for increased flexibility
- I<sup>2</sup>C <sup>[4]</sup> functionality to implement an I<sup>2</sup>C master and slave
- An internal voltage reference, multi-master, that provides an absolute value of 1.3 V to a number of PSoC subsystems
- A SMP that generates normal operating voltages from a single battery cell
- Various system resets supported by the M8C

The digital system consists of an array of digital PSoC blocks that may be configured into any number of digital peripherals. The digital blocks are connected to the GPIOs through a series of global buses. These buses can route any signal to any pin, freeing designs from the constraints of a fixed peripheral controller.

The analog system consists of four analog PSoC blocks, supporting comparators, and analog-to-digital conversion up to 10 bits of precision.

### The Digital System

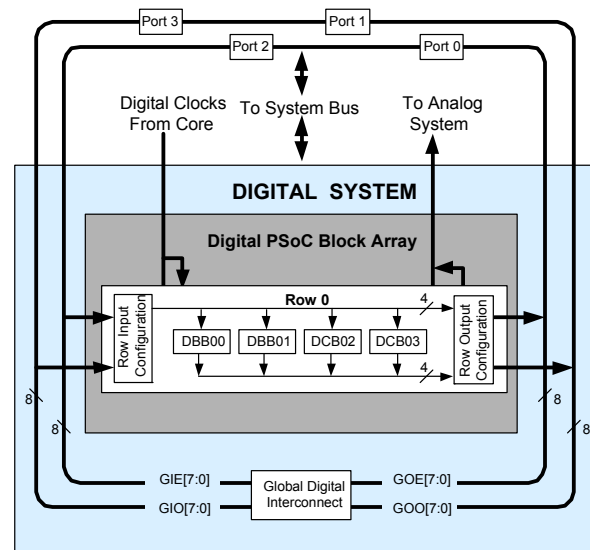
The digital system consists of four digital PSoC blocks. Each block is an 8-bit resource that is used alone or combined with other blocks to form 8-, 16-, 24-, and 32-bit peripherals, which are called user modules. Digital peripheral configurations include:

- PWMs (8- to 32-bit)
- PWMs with dead band (8- to 32-bit)
- Counters (8- to 32-bit)
- Timers (8- to 32-bit)
- UART 8- with selectable parity
- Serial peripheral interface (SPI) master and slave
- I<sup>2</sup>C slave and multi-master <sup>[4]</sup>
- CRC/generator (8-bit)
- IrDA
- PRS generators (8-bit to 32-bit)

The digital blocks are connected to any GPIO through a series of global buses that can route any signal to any pin. The buses also allow for signal multiplexing and for performing logic operations. This configurability frees your designs from the constraints of a fixed peripheral controller.

Digital blocks are provided in rows of four, where the number of blocks varies by PSoC device family. This allows the optimum choice of system resources for your application. Family resources are shown in [Table 1 on page 6](#).

**Figure 2. Digital System Block Diagram**



### Notes

3. **Errata:** The worst case IMO frequency deviation when operated below 0 °C and above +70 °C and within the upper and lower datasheet temperature range is ±5%.
4. **Errata:** The I<sup>2</sup>C block exhibits occasional data and bus corruption errors when the I<sup>2</sup>C master initiates transactions while the device is transitioning in to or out of sleep mode.

## PSoC Device Characteristics

Depending on your PSoC device characteristics, the digital and analog systems can have 16, 8, or 4 digital blocks and 12, 6, or 4 analog blocks. [Table 1](#) lists the resources available for specific PSoC device groups. The PSoC device covered by this datasheet is highlighted in [Table 1](#).

**Table 1. PSoC Device Characteristics**

PSoC Part Number	Digital I/O	Digital Rows	Digital Blocks	Analog Inputs	Analog Outputs	Analog Columns	Analog Blocks	SRAM Size	Flash Size
CY8C29x66	up to 64	4	16	up to 12	4	4	12	2 K	32 K
CY8C28xxx	up to 44	up to 3	up to 12	up to 44	up to 4	up to 6	up to 12 + 4 <sup>[6]</sup>	1 K	16 K
CY8C27x43	up to 44	2	8	up to 12	4	4	12	256	16 K
CY8C24x94	up to 56	1	4	up to 48	2	2	6	1 K	16 K
CY8C24x23A	up to 24	1	4	up to 12	2	2	6	256	4 K
CY8C23x33	up to 26	1	4	up to 12	2	2	4	256	8 K
CY8C22x45	up to 38	2	8	up to 38	0	4	6 <sup>[6]</sup>	1 K	16 K
CY8C21x45	up to 24	1	4	up to 24	0	4	6 <sup>[6]</sup>	512	8 K
CY8C21x34	up to 28	1	4	up to 28	0	2	4 <sup>[6]</sup>	512	8 K
CY8C21x23	up to 16	1	4	up to 8	0	2	4 <sup>[6]</sup>	256	4 K
CY8C20x34	up to 28	0	0	up to 28	0	0	3 <sup>[6,7]</sup>	512	8 K
CY8C20xx6	up to 36	0	0	up to 36	0	0	3 <sup>[6,7]</sup>	up to 2 K	up to 32 K

## Getting Started

For in-depth information, along with detailed programming details, see the *PSoC® Technical Reference Manual*.

For up-to-date ordering, packaging, and electrical specification information, see the latest [PSoC device datasheets](#) on the web.

## Application Notes

[Cypress application notes](#) are an excellent introduction to the wide variety of possible PSoC designs.

## Development Kits

[PSoC Development Kits](#) are available online from and through a growing number of regional and global distributors, which include Arrow, Avnet, Digi-Key, Farnell, Future Electronics, and Newark.

## Training

[Free PSoC technical training](#) (on demand, webinars, and workshops), which is available online via [www.cypress.com](http://www.cypress.com),

covers a wide variety of topics and skill levels to assist you in your designs.

## CYPros Consultants

Certified PSoC consultants offer everything from technical assistance to completed PSoC designs. To contact or become a PSoC consultant go to the [CYPros Consultants](#) web site.

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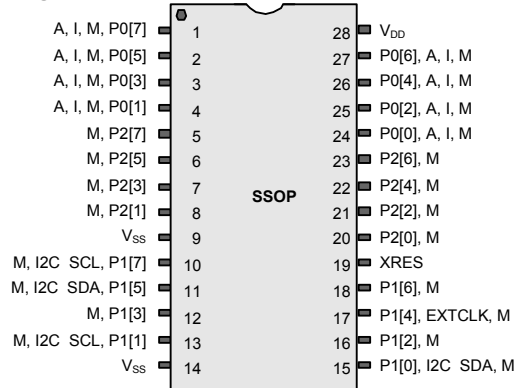
### Notes

6. Limited analog functionality.

7. Two analog blocks and one CapSense®.

## 28-pin Part Pinout

**Figure 6. CY8C21534 28-pin PSoc Device**



## CY8C21534 28-pin SSOP Pin Definitions

Pin No.	Type		Name	Description
	Digital	Analog		
1	I/O	I, M	P0[7]	Analog column mux input
2	I/O	I, M	P0[5]	Analog column mux input and column output
3	I/O	I, M	P0[3]	Analog column mux input and column output, integrating input
4	I/O	I, M	P0[1]	Analog column mux input, integrating input
5	I/O	M	P2[7]	
6	I/O	M	P2[5]	
7	I/O	I, M	P2[3]	Direct switched capacitor block input
8	I/O	I, M	P2[1]	Direct switched capacitor block input
9	Power		V <sub>SS</sub>	Ground connection <sup>[13]</sup>
10	I/O	M	P1[7]	I <sup>2</sup> C SCL
11	I/O	M	P1[5]	I <sup>2</sup> C SDA
12	I/O	M	P1[3]	
13	I/O	M	P1[1]	I <sup>2</sup> C SCL, ISSP-SCLK <sup>[14]</sup>
14	Power		V <sub>SS</sub>	Ground connection <sup>[13]</sup>
15	I/O	M	P1[0]	I <sup>2</sup> C SDA, ISSP-SDATA <sup>[14]</sup>
16	I/O	M	P1[2]	
17	I/O	M	P1[4]	Optional external clock input (EXTCLK)
18	I/O	M	P1[6]	
19	Input		XRES	Active high external reset with internal pull-down
20	I/O	I, M	P2[0]	Direct switched capacitor block input
21	I/O	I, M	P2[2]	Direct switched capacitor block input
22	I/O	M	P2[4]	
23	I/O	M	P2[6]	
24	I/O	I, M	P0[0]	Analog column mux input
25	I/O	I, M	P0[2]	Analog column mux input
26	I/O	I, M	P0[4]	Analog column mux input
27	I/O	I, M	P0[6]	Analog column mux input
28	Power		V <sub>DD</sub>	Supply voltage

**LEGEND** A: Analog, I: Input, O = Output, and M = Analog Mux Input.

### Notes

13. All V<sub>SS</sub> pins should be brought out to one common GND plane.

14. These are the ISSP pins, which are not high Z at POR. See the [PSoc Technical Reference Manual](#) for details.

**CY8C21434/CY8C21634 32-pin QFN Pin Definitions**

Pin No. <sup>[15]</sup>	Type		Name	Description
	Digital	Analog		
1	I/O	I, M	P0[1]	Analog column mux input, integrating input
2	I/O	M	P2[7]	
3	I/O	M	P2[5]	
4	I/O	M	P2[3]	
5	I/O	M	P2[1]	
6	I/O	M	P3[3]	In CY8C21434 part
6	Power		SMP	SMP connection to required external components in CY8C21634 part
7	I/O	M	P3[1]	In CY8C21434 part
7	Power		V <sub>SS</sub>	Ground connection in CY8C21634 part <sup>[16]</sup>
8	I/O	M	P1[7]	I <sup>2</sup> C SCL
9	I/O	M	P1[5]	I <sup>2</sup> C SDA
10	I/O	M	P1[3]	
11	I/O	M	P1[1]	I <sup>2</sup> C SCL, ISSP-SCLK <sup>[17]</sup>
12	Power		V <sub>SS</sub>	Ground connection <sup>[16]</sup>
13	I/O	M	P1[0]	I <sup>2</sup> C SDA, ISSP-SDATA <sup>[17]</sup>
14	I/O	M	P1[2]	
15	I/O	M	P1[4]	Optional external clock input (EXTCLK)
16	I/O	M	P1[6]	
17	Input		XRES	Active high external reset with internal pull-down
18	I/O	M	P3[0]	
19	I/O	M	P3[2]	
20	I/O	M	P2[0]	
21	I/O	M	P2[2]	
22	I/O	M	P2[4]	
23	I/O	M	P2[6]	
24	I/O	I, M	P0[0]	Analog column mux input
25	I/O	I, M	P0[2]	Analog column mux input
26	I/O	I, M	P0[4]	Analog column mux input
27	I/O	I, M	P0[6]	Analog column mux input
28	Power		V <sub>DD</sub>	Supply voltage
29	I/O	I, M	P0[7]	Analog column mux input
30	I/O	I, M	P0[5]	Analog column mux input
31	I/O	I, M	P0[3]	Analog column mux input, integrating input
32	Power		V <sub>SS</sub>	Ground connection <sup>[16]</sup>

**LEGEND** A = Analog, I = Input, O = Output, and M = Analog Mux Input.

**Notes**

15. The center pad on the QFN package must be connected to ground (V<sub>SS</sub>) for best mechanical, thermal, and electrical performance. If not connected to ground, it must be electrically floated and not connected to any other signal.
16. All V<sub>SS</sub> pins should be brought out to one common GND plane.
17. These are the ISSP pins, which are not high Z at POR. See the [PSoC Technical Reference Manual](#) for details.

**CY8C21001 56-pin SSOP Pin Definitions** (continued)

Pin No.	Type		Pin Name	Description
	Digital	Analog		
20	I/O		P3[1]	
21			NC	No connection. Pin must be left floating
22			NC	No connection. Pin must be left floating
23	I/O		P1[7]	I <sup>2</sup> C SCL
24	I/O		P1[5]	I <sup>2</sup> C SDA
25			NC	No connection. Pin must be left floating
26	I/O		P1[3]	I <sub>FMTEST</sub>
27	I/O		P1[1]	I <sup>2</sup> C SCL, ISSP-SCLK <sup>[19]</sup>
28	Power		V <sub>SS</sub>	Ground connection <sup>[18]</sup>
29			NC	No connection. Pin must be left floating
30			NC	No connection. Pin must be left floating
31	I/O		P1[0]	I <sup>2</sup> C SDA, ISSP-SDATA <sup>[19]</sup>
32	I/O		P1[2]	V <sub>FMTEST</sub>
33	I/O		P1[4]	Optional external clock input (EXTCLK)
34	I/O		P1[6]	
35			NC	No connection. Pin must be left floating
36			NC	No connection. Pin must be left floating
37			NC	No connection. Pin must be left floating
38			NC	No connection. Pin must be left floating
39			NC	No connection. Pin must be left floating
40			NC	No connection. Pin must be left floating
41	Input		XRES	Active high external reset with internal pull-down
42	OCD		HCLK	OCD high-speed clock output
43	OCD		CCLK	OCD CPU clock output
44	I/O		P3[0]	
45	I/O		P3[2]	
46			NC	No connection. Pin must be left floating
47			NC	No connection. Pin must be left floating
48	I/O	I	P2[0]	
49	I/O	I	P2[2]	
50	I/O		P2[4]	
51	I/O		P2[6]	
52	I/O	I	P0[0]	Analog column mux input
53	I/O	I	P0[2]	Analog column mux input and column output
54	I/O	I	P0[4]	Analog column mux input and column output
55	I/O	I	P0[6]	Analog column mux input
56	Power		V <sub>DD</sub>	Supply voltage

**LEGEND:** A = Analog, I = Input, O = Output, and OCD = On-Chip Debug.

**Notes**

18. All V<sub>SS</sub> pins should be brought out to one common GND plane.

19. These are the ISSP pins, which are not High Z at POR. See the [PSoC Technical Reference Manual](#) for details.

## Register Reference

This chapter lists the registers of the CY8C21x34 PSoC device. For detailed register information, see the [PSoC Technical Reference Manual](#).

### Register Conventions

The register conventions specific to this section are listed in [Table 2](#).

**Table 2. Register Conventions**

Convention	Description
R	Read register or bit(s)
W	Write register or bit(s)
L	Logical register or bit(s)
C	Clearable register or bit(s)
#	Access is bit specific

### Register Mapping Tables

The PSoC device has a total register address space of 512 bytes. The register space is referred to as I/O space and is divided into two banks, Bank 0 and Bank 1. The XO1 bit in the Flag register (CPU\_F) determines which bank the user is currently in. When the XO1 bit is set to 1, the user is in Bank 1.

**Note** In the following register mapping tables, blank fields are reserved and must not be accessed.

## Absolute Maximum Ratings

Symbol	Description	Min	Typ	Max	Units	Notes
T <sub>STG</sub>	Storage temperature	–55	25	+100	°C	Higher storage temperatures reduce data retention time. Recommended storage temperature is +25 °C ± 25 °C. Extended duration storage temperatures above 65 °C degrade reliability.
T <sub>BAKETEMP</sub>	Bake temperature	–	125	See package label	°C	
t <sub>BAKETIME</sub>	Bake time	See package label	–	72	Hours	
T <sub>A</sub>	Ambient temperature with power applied	–40	–	+85	°C	
V <sub>DD</sub>	Supply voltage on V <sub>DD</sub> relative to V <sub>SS</sub>	–0.5	–	+6.0	V	
V <sub>IO</sub>	DC input voltage	V <sub>SS</sub> – 0.5	–	V <sub>DD</sub> + 0.5	V	
V <sub>IOZ</sub>	DC voltage applied to tri-state	V <sub>SS</sub> – 0.5	–	V <sub>DD</sub> + 0.5	V	
I <sub>MIO</sub>	Maximum current into any port pin	–25	–	+50	mA	
ESD	Electrostatic discharge voltage	2000	–	–	V	Human body model ESD.
LU	Latch-up current	–	–	200	mA	

## Operating Temperature

Symbol	Description	Min	Typ	Max	Units	Notes
T <sub>A</sub>	Ambient temperature	–40	–	+85	°C	
T <sub>J</sub>	Junction temperature	–40	–	+100	°C	The temperature rise from ambient to junction is package specific. See <a href="#">Table 29 on page 38</a> . You must limit the power consumption to comply with this requirement.



### DC Operational Amplifier Specifications

The following tables list the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , 3.0 V to 3.6 V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , or 2.4 V to 3.0 V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , respectively. Typical parameters are measured at 5 V, 3.3 V, or 2.7 V at  $25^{\circ}\text{C}$  and are for design guidance only.

**Table 8. 5-V DC Operational Amplifier Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
$V_{\text{OSOA}}$	Input offset voltage (absolute value)	–	2.5	15	mV	
$\text{TCV}_{\text{OSOA}}$	Average input offset voltage drift	–	10	–	$\mu\text{V}/^{\circ}\text{C}$	
$I_{\text{EBOA}}$	Input leakage current (Port 0 analog pins 7-to-1)	–	200	–	pA	Gross tested to 1 $\mu\text{A}$
$I_{\text{EBOA00}}$	Input leakage current (Port 0, Pin 0 analog pin)	–	50	–	nA	Gross tested to 1 $\mu\text{A}$
$C_{\text{INOA}}$	Input capacitance (Port 0 analog pins)	–	4.5	9.5	pF	Package and pin dependent. Temp = $25^{\circ}\text{C}$
$V_{\text{CMOA}}$	Common mode voltage range	0.0	–	$V_{\text{DD}} - 1.0$	V	
$G_{\text{OLOA}}$	Open loop gain	–	80	–	dB	
$I_{\text{SOA}}$	Amplifier supply current	–	10	30	$\mu\text{A}$	

**Table 9. 3.3-V DC Operational Amplifier Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
$V_{\text{OSOA}}$	Input offset voltage (absolute value)	–	2.5	15	mV	
$\text{TCV}_{\text{OSOA}}$	Average input offset voltage drift	–	10	–	$\mu\text{V}/^{\circ}\text{C}$	
$I_{\text{EBOA}}$	Input leakage current (Port 0 analog pins)	–	200	–	pA	Gross tested to 1 $\mu\text{A}$
$I_{\text{EBOA00}}$	Input leakage current (Port 0, Pin 0 analog pin)	–	50	–	nA	Gross tested to 1 $\mu\text{A}$
$C_{\text{INOA}}$	Input capacitance (Port 0 analog pins)	–	4.5	9.5	pF	Package and pin dependent. Temp = $25^{\circ}\text{C}$
$V_{\text{CMOA}}$	Common mode voltage range	0	–	$V_{\text{DD}} - 1.0$	V	
$G_{\text{OLOA}}$	Open loop gain	–	80	–	dB	
$I_{\text{SOA}}$	Amplifier supply current	–	10	30	$\mu\text{A}$	

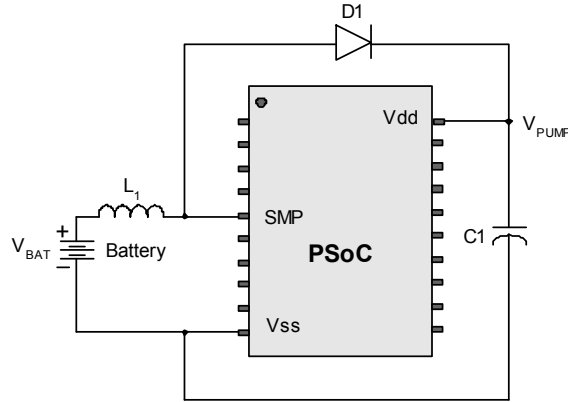
**Table 10. 2.7-V DC Operational Amplifier Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
$V_{\text{OSOA}}$	Input offset voltage (absolute value)	–	2.5	15	mV	
$\text{TCV}_{\text{OSOA}}$	Average input offset voltage drift	–	10	–	$\mu\text{V}/^{\circ}\text{C}$	
$I_{\text{EBOA}}$	Input leakage current (Port 0 analog pins)	–	200	–	pA	Gross tested to 1 $\mu\text{A}$
$I_{\text{EBOA00}}$	Input leakage current (Port 0, Pin 0 analog pin)	–	50	–	nA	Gross tested to 1 $\mu\text{A}$
$C_{\text{INOA}}$	Input capacitance (Port 0 analog pins)	–	4.5	9.5	pF	Package and pin dependent. Temp = $25^{\circ}\text{C}$
$V_{\text{CMOA}}$	Common mode voltage range	0	–	$V_{\text{DD}} - 1.0$	V	
$G_{\text{OLOA}}$	Open loop gain	–	80	–	dB	
$I_{\text{SOA}}$	Amplifier supply current	–	10	30	$\mu\text{A}$	

### DC Switch Mode Pump Specifications

Table 11 lists the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , 3.0 V to 3.6 V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , or 2.4 V to 3.0 V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , respectively. Typical parameters are measured at 5 V, 3.3 V, or 2.7 V at  $25^{\circ}\text{C}$  and are for design guidance only.

**Figure 12. Basic Switch Mode Pump Circuit**



**Table 11. DC Switch Mode Pump (SMP) Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
V <sub>PUMP5V</sub>	5 V output voltage from pump	4.75	5.0	5.25	V	Configured as in Note 20 Average, neglecting ripple SMP trip voltage is set to 5.0 V
V <sub>PUMP3V</sub>	3.3 V output voltage from pump	3.00	3.25	3.60	V	Configured as in Note 20 Average, neglecting ripple. SMP trip voltage is set to 3.25 V
V <sub>PUMP2V</sub>	2.6 V output voltage from pump	2.45	2.55	2.80	V	Configured as in Note 20 Average, neglecting ripple. SMP trip voltage is set to 2.55 V
I <sub>PUMP</sub>	Available output current V <sub>BAT</sub> = 1.8 V, V <sub>PUMP</sub> = 5.0 V V <sub>BAT</sub> = 1.5 V, V <sub>PUMP</sub> = 3.25 V V <sub>BAT</sub> = 1.3 V, V <sub>PUMP</sub> = 2.55 V	5 8 8	— — —	— — —	mA mA mA	Configured as in Note 20 SMP trip voltage is set to 5.0 V SMP trip voltage is set to 3.25 V SMP trip voltage is set to 2.55 V
V <sub>BAT5V</sub>	Input voltage range from battery	1.8	—	5.0	V	Configured as in Note 20 SMP trip voltage is set to 5.0 V
V <sub>BAT3V</sub>	Input voltage range from battery	1.0	—	3.3	V	Configured as in Note 20 SMP trip voltage is set to 3.25 V
V <sub>BAT2V</sub>	Input voltage range from battery	1.0	—	2.8	V	Configured as in Note 20 SMP trip voltage is set to 2.55 V
V <sub>BATSTART</sub>	Minimum input voltage from battery to start pump	1.2	—	—	V	Configured as in Note 20 0 °C ≤ T <sub>A</sub> ≤ 100. 1.25 V at T <sub>A</sub> = -40 °C
ΔV <sub>PUMP_Line</sub>	Line regulation (over V <sub>i</sub> range)	—	5	—	%V <sub>O</sub>	Configured as in Note 20 V <sub>O</sub> is the "V <sub>DD</sub> Value for PUMP Trip" specified by the VM[2:0] setting in the DC POR and LVD Specification, Table 13 on page 24
ΔV <sub>PUMP_Load</sub>	Load regulation	—	5	—	%V <sub>O</sub>	Configured as in Note 20 V <sub>O</sub> is the "V <sub>DD</sub> Value for PUMP Trip" specified by the VM[2:0] setting in the DC POR and LVD Specification, Table 13 on page 24
ΔV <sub>PUMP_Ripple</sub>	Output voltage ripple (depends on cap/load)	—	100	—	mVpp	Configured as in Note 20 Load is 5 mA
E <sub>3</sub>	Efficiency	35	50	—	%	Configured as in Note 20 Load is 5 mA. SMP trip voltage is set to 3.25 V

**Note**

20. L<sub>1</sub> = 2 mH inductor, C<sub>1</sub> = 10 mF capacitor, D<sub>1</sub> = Schottky diode. See Figure 12 on page 23.

### AC Digital Block Specifications

The following tables list the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , 3.0 V to 3.6 V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , or 2.4 V to 3.0 V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , respectively. Typical parameters are measured at 5 V, 3.3 V, or 2.7 V at  $25^{\circ}\text{C}$  and are for design guidance only.

**Table 21. 5-V and 3.3-V AC Digital Block Specifications**

Function	Description	Min	Typ	Max	Unit	Notes
All functions	Block input clock frequency					
	$V_{DD} \geq 4.75\text{ V}$	–	–	49.2	MHz	
	$V_{DD} < 4.75\text{ V}$	–	–	24.6	MHz	
Timer	Input clock frequency					
	No capture, $V_{DD} \geq 4.75\text{ V}$	–	–	49.2	MHz	
	No capture, $V_{DD} < 4.75\text{ V}$	–	–	24.6	MHz	
	With capture	–	–	24.6	MHz	
	Capture pulse width	50 <sup>[37]</sup>	–	–	ns	
Counter	Input clock frequency					
	No enable input, $V_{DD} \geq 4.75\text{ V}$	–	–	49.2	MHz	
	No enable input, $V_{DD} < 4.75\text{ V}$	–	–	24.6	MHz	
	With enable input	–	–	24.6	MHz	
	Enable input pulse width	50 <sup>[37]</sup>	–	–	ns	
Dead Band	Kill pulse width					
	Asynchronous restart mode	20	–	–	ns	
	Synchronous restart mode	50 <sup>[37]</sup>	–	–	ns	
	Disable mode	50 <sup>[37]</sup>	–	–	ns	
	Input clock frequency					
	$V_{DD} \geq 4.75\text{ V}$	–	–	49.2	MHz	
	$V_{DD} < 4.75\text{ V}$	–	–	24.6	MHz	
CRCPRS (PRS Mode)	Input clock frequency					
	$V_{DD} \geq 4.75\text{ V}$	–	–	49.2	MHz	
	$V_{DD} < 4.75\text{ V}$	–	–	24.6	MHz	
CRCPRS (CRC Mode)	Input clock frequency	–	–	24.6	MHz	
SPIM	Input clock frequency	–	–	8.2	MHz	The SPI serial clock (SCLK) frequency is equal to the input clock frequency divided by 2.
SPIS	Input clock (SCLK) frequency	–	–	4.1	MHz	The input clock is the SPI SCLK in SPIS mode.
	Width of SS_negated between transmissions	50 <sup>[37]</sup>	–	–	ns	
Transmitter	Input clock frequency					The baud rate is equal to the input clock frequency divided by 8.
	$V_{DD} \geq 4.75\text{ V}$ , 2 stop bits	–	–	49.2	MHz	
	$V_{DD} \geq 4.75\text{ V}$ , 1 stop bit	–	–	24.6	MHz	
	$V_{DD} < 4.75\text{ V}$	–	–	24.6	MHz	
Receiver	Input clock frequency					The baud rate is equal to the input clock frequency divided by 8.
	$V_{DD} \geq 4.75\text{ V}$ , 2 stop bits	–	–	49.2	MHz	
	$V_{DD} \geq 4.75\text{ V}$ , 1 stop bit	–	–	24.6	MHz	
	$V_{DD} < 4.75\text{ V}$	–	–	24.6	MHz	

**Note**

37. 50 ns minimum input pulse width is based on the input synchronizers running at 24 MHz (42 ns nominal period).

**Table 22. 2.7-V AC Digital Block Specifications**

Function	Description	Min	Typ	Max	Units	Notes
All functions	Block input clock frequency	–	–	12.7	MHz	2.4 V < V <sub>DD</sub> < 3.0 V
Timer	Capture pulse width	100 <sup>[38]</sup>	–	–	ns	
	Input clock frequency, with or without capture	–	–	12.7	MHz	
Counter	Enable input pulse width	100	–	–	ns	
	Input clock frequency, no enable input	–	–	12.7	MHz	
	Input clock frequency, enable input	–	–	12.7	MHz	
Dead Band	Kill pulse width:					
	Asynchronous restart mode	20	–	–	ns	
	Synchronous restart mode	100	–	–	ns	
	Disable mode	100	–	–	ns	
	Input clock frequency	–	–	12.7	MHz	
CRCPRS (PRS Mode)	Input clock frequency	–	–	12.7	MHz	
CRCPRS (CRC Mode)	Input clock frequency	–	–	12.7	MHz	
SPIM	Input clock frequency	–	–	6.35	MHz	The SPI serial clock (SCLK) frequency is equal to the input clock frequency divided by 2.
SPIS	Input clock (SCLK) frequency	–	–	4.1	MHz	
	Width of SS_ Negated between transmissions	100	–	–	ns	
Transmitter	Input clock frequency	–	–	12.7	MHz	The baud rate is equal to the input clock frequency divided by 8.
Receiver	Input clock frequency	–	–	12.7	MHz	The baud rate is equal to the input clock frequency divided by 8.

#### AC External Clock Specifications

The following tables list the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , or 3.0 V to 3.6 V and  $-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ , respectively. Typical parameters are measured at 5 V, 3.3 V, or 2.7 V at 25 °C and are for design guidance only.

**Table 23. 5-V AC External Clock Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
F <sub>OSCEXT</sub>	Frequency	0.093	–	24.6	MHz	
–	High period	20.6	–	5300	ns	
–	Low period	20.6	–	–	ns	
–	Power-up IMO to switch	150	–	–	μs	

#### Note

38. 100 ns minimum input pulse width is based on the input synchronizers running at 12 MHz (84 ns nominal period).

**Table 24. 3.3-V AC External Clock Specifications**

Symbol	Description	Min	Typ	Max	Units	Notes
F <sub>OSCEXT</sub>	Frequency with CPU clock divide by 1	0.093	–	12.3	MHz	Maximum CPU frequency is 12 MHz at 3.3 V. With the CPU clock divider set to 1, the external clock must adhere to the maximum frequency and duty cycle requirements
F <sub>OSCEXT</sub>	Frequency with CPU clock divide by 2 or greater	0.186	–	24.6	MHz	If the frequency of the external clock is greater than 12 MHz, the CPU clock divider must be set to 2 or greater. In this case, the CPU clock divider ensures that the fifty percent duty cycle requirement is met
–	High period with CPU clock divide by 1	41.7	–	5300	ns	
–	Low period with CPU clock divide by 1	41.7	–	–	ns	
–	Power-up IMO to switch	150	–	–	μs	

**Table 25. 2.7-V AC External Clock Specifications**

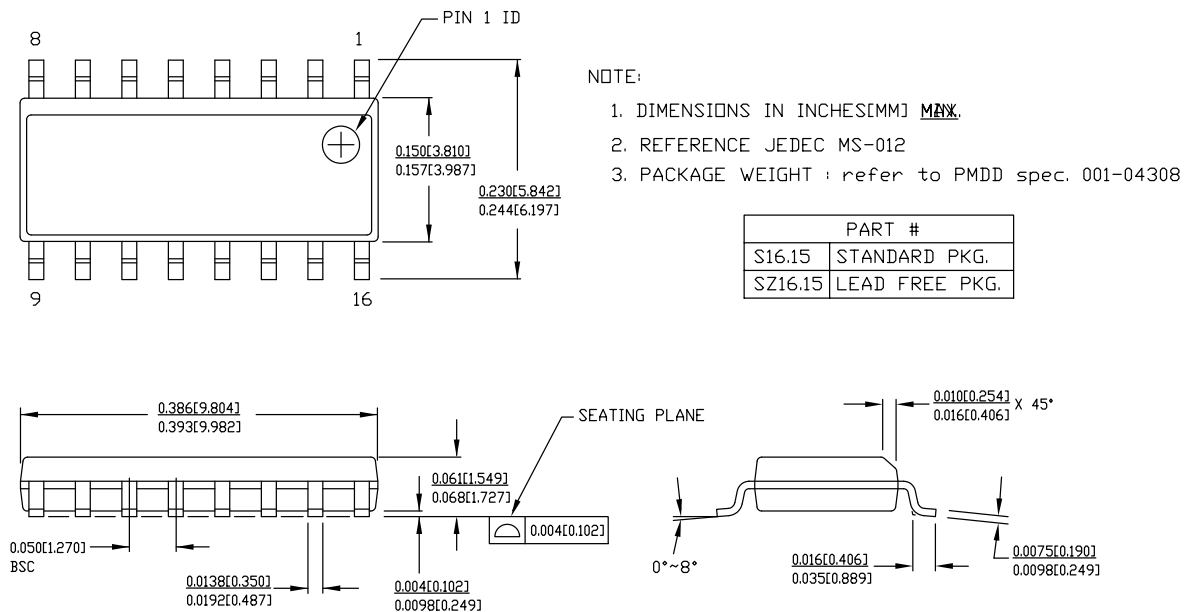
Symbol	Description	Min	Typ	Max	Units	Notes
F <sub>OSCEXT</sub>	Frequency with CPU clock divide by 1	0.093	–	3.08	MHz	Maximum CPU frequency is 3 MHz at 2.7 V. With the CPU clock divider set to 1, the external clock must adhere to the maximum frequency and duty cycle requirements
F <sub>OSCEXT</sub>	Frequency with CPU clock divide by 2 or greater	0.186	–	6.35	MHz	If the frequency of the external clock is greater than 3 MHz, the CPU clock divider must be set to 2 or greater. In this case, the CPU clock divider ensures that the fifty percent duty cycle requirement is met
–	High period with CPU clock divide by 1	160	–	5300	ns	
–	Low period with CPU clock divide by 1	160	–	–	ns	
–	Power-up IMO to switch	150	–	–	μs	

## Packaging Information

This section shows the packaging specifications for the CY8C21x34 PSoC device with the thermal impedances for each package.

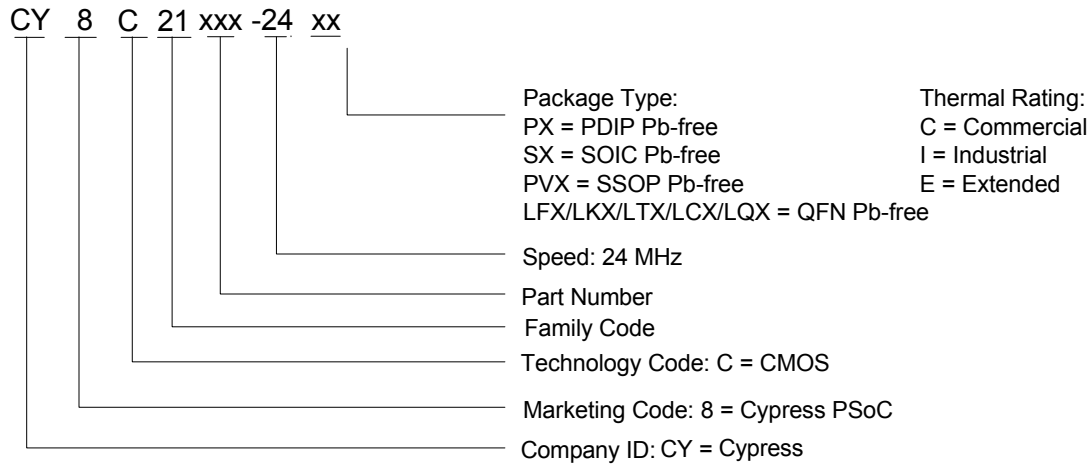
**Important Note** Emulation tools may require a larger area on the target PCB than the chip's footprint. For a detailed description of the emulation tools' dimensions, refer to the emulator pod drawings at <http://www.cypress.com>.

**Figure 15. 16-pin SOIC (150 Mils) Package Outline, 51-85068**



51-85068 \*E

## Ordering Code Definitions



## Document Conventions

### Units of Measure

Table 33 lists the units of measures.

**Table 33. Units of Measure**

Symbol	Unit of Measure	Symbol	Unit of Measure
kB	1024 bytes	μH	micro henry
dB	decibels	μs	microsecond
°C	degree Celsius	ms	millisecond
μF	microfarad	ns	nanosecond
fF	femto farad	ps	picosecond
pF	picofarad	μV	microvolt
kHz	kilohertz	mV	millivolts
MHz	megahertz	mVpp	millivolts peak-to-peak
rt-Hz	root hertz	nV	nano volt
kΩ	kilo ohm	V	volt
Ω	ohm	μW	microwatt
μA	microampere	W	watt
mA	milliampere	mm	millimeter
nA	nano ampere	ppm	parts per million
pA	pico ampere	%	percent
mH	millihenry		

### Numeric Conventions

Hexadecimal numbers are represented with all letters in uppercase with an appended lowercase 'h' (for example, '14h' or '3Ah'). Hexadecimal numbers may also be represented by a '0x' prefix, the C coding convention. Binary numbers have an appended lowercase 'b' (for example, '01010100b' or '01000011b'). Numbers not indicated by an 'h' or 'b' are decimals.

## Glossary

active high	<ol style="list-style-type: none"> <li>1. A logic signal having its asserted state as the logic 1 state.</li> <li>2. A logic signal having the logic 1 state as the higher voltage of the two states.</li> </ol>
analog blocks	The basic programmable opamp circuits. These are SC (switched capacitor) and CT (continuous time) blocks. These blocks can be interconnected to provide ADCs, DACs, multi-pole filters, gain stages, and much more.
analog-to-digital (ADC)	A device that changes an analog signal to a digital signal of corresponding magnitude. Typically, an ADC converts a voltage to a digital number. The digital-to-analog (DAC) converter performs the reverse operation.
Application programming interface (API)	A series of software routines that comprise an interface between a computer application and lower level services and functions (for example, user modules and libraries). APIs serve as building blocks for programmers that create software applications.
asynchronous	A signal whose data is acknowledged or acted upon immediately, irrespective of any clock signal.
bandgap reference	A stable voltage reference design that matches the positive temperature coefficient of $V_T$ with the negative temperature coefficient of $V_{BE}$ , to produce a zero temperature coefficient (ideally) reference.
bandwidth	<ol style="list-style-type: none"> <li>1. The frequency range of a message or information processing system measured in hertz.</li> <li>2. The width of the spectral region over which an amplifier (or absorber) has substantial gain (or loss); it is sometimes represented more specifically as, for example, full width at half maximum.</li> </ol>



## Glossary (continued)

microcontroller	An integrated circuit chip that is designed primarily for control systems and products. In addition to a CPU, a microcontroller typically includes memory, timing circuits, and IO circuitry. The reason for this is to permit the realization of a controller with a minimal quantity of chips, thus achieving maximal possible miniaturization. This in turn, reduces the volume and the cost of the controller. The microcontroller is normally not used for general-purpose computation as is a microprocessor.
mixed-signal	The reference to a circuit containing both analog and digital techniques and components.
modulator	A device that imposes a signal on a carrier.
noise	<ol style="list-style-type: none"> <li>1. A disturbance that affects a signal and that may distort the information carried by the signal.</li> <li>2. The random variations of one or more characteristics of any entity such as voltage, current, or data.</li> </ol>
oscillator	A circuit that may be crystal controlled and is used to generate a clock frequency.
parity	A technique for testing transmitting data. Typically, a binary digit is added to the data to make the sum of all the digits of the binary data either always even (even parity) or always odd (odd parity).
Phase-locked loop (PLL)	An electronic circuit that controls an <b>oscillator</b> so that it maintains a constant phase angle relative to a reference signal.
pinouts	The pin number assignment: the relation between the logical inputs and outputs of the PSoC device and their physical counterparts in the printed circuit board (PCB) package. Pinouts involve pin numbers as a link between schematic and PCB design (both being computer generated files) and may also involve pin names.
port	A group of pins, usually eight.
Power on reset (POR)	A circuit that forces the PSoC device to reset when the voltage is below a pre-set level. This is one type of hardware reset.
PSoC®	Cypress Semiconductor's PSoC® is a registered trademark and Programmable System-on-Chip™ is a trademark of Cypress.
PSoC Designer™	The software for Cypress' Programmable System-on-Chip technology.
pulse width modulator (PWM)	An output in the form of duty cycle which varies as a function of the applied measurand
RAM	An acronym for random access memory. A data-storage device from which data can be read out and new data can be written in.
register	A storage device with a specific capacity, such as a bit or byte.
reset	A means of bringing a system back to a know state. See hardware reset and software reset.
ROM	An acronym for read only memory. A data-storage device from which data can be read out, but new data cannot be written in.
serial	<ol style="list-style-type: none"> <li>1. Pertaining to a process in which all events occur one after the other.</li> <li>2. Pertaining to the sequential or consecutive occurrence of two or more related activities in a single device or channel.</li> </ol>
settling time	The time it takes for an output signal or value to stabilize after the input has changed from one value to another.

## Glossary (continued)

shift register	A memory storage device that sequentially shifts a word either left or right to output a stream of serial data.
slave device	A device that allows another device to control the timing for data exchanges between two devices. Or when devices are cascaded in width, the slave device is the one that allows another device to control the timing of data exchanges between the cascaded devices and an external interface. The controlling device is called the master device.
SRAM	An acronym for static random access memory. A memory device where you can store and retrieve data at a high rate of speed. The term static is used because, after a value is loaded into an SRAM cell, it remains unchanged until it is explicitly altered or until power is removed from the device.
SROM	An acronym for supervisory read only memory. The SROM holds code that is used to boot the device, calibrate circuitry, and perform Flash operations. The functions of the SROM may be accessed in normal user code, operating from Flash.
stop bit	A signal following a character or block that prepares the receiving device to receive the next character or block.
synchronous	<ol style="list-style-type: none"> <li>1. A signal whose data is not acknowledged or acted upon until the next active edge of a clock signal.</li> <li>2. A system whose operation is synchronized by a clock signal.</li> </ol>
tri-state	A function whose output can adopt three states: 0, 1, and Z (high-impedance). The function does not drive any value in the Z state and, in many respects, may be considered to be disconnected from the rest of the circuit, allowing another output to drive the same net.
UART	A UART or universal asynchronous receiver-transmitter translates between parallel bits of data and serial bits.
user modules	Pre-build, pre-tested hardware/firmware peripheral functions that take care of managing and configuring the lower level Analog and Digital PSoC Blocks. User Modules also provide high level <b>API (Application Programming Interface)</b> for the peripheral function.
user space	The bank 0 space of the register map. The registers in this bank are more likely to be modified during normal program execution and not just during initialization. Registers in bank 1 are most likely to be modified only during the initialization phase of the program.
V <sub>DD</sub>	A name for a power net meaning "voltage drain." The most positive power supply signal. Usually 5 V or 3.3 V.
V <sub>SS</sub>	A name for a power net meaning "voltage source." The most negative power supply signal.
watchdog timer	A timer that must be serviced periodically. If it is not serviced, the CPU resets after a specified period of time.

## Errata

This section describes the errata for the PSoC® Programmable System-on-Chip CY8C21X34. Details include errata trigger conditions, scope of impact, available workarounds, and silicon revision applicability.

Contact your local Cypress Sales Representative if you have questions.

### Part Numbers Affected

Part Number	Ordering Information
CY8C21X34	CY8C21234-24SXI
	CY8C21234-24SXIT
	CY8C21334-24PVXI
	CY8C21334-24PVXIT
	CY8C21534-24PVXI
	CY8C21534-24PVXIT
	CY8C21434-24LFXI
	CY8C21434-24LFXIT
	CY8C21434-24LKXI
	CY8C21434-24LKXIT
	CY8C21634-24LFXI
	CY8C21634-24LFXIT
	CY8C21434-24LTXI
	CY8C21434-24LTXIT
	CY8C21434-24LQXI
	CY8C21434-24LQXIT
	CY8C21634-24LTXI
	CY8C21634-24LTXIT
	CY8C21001-24PVXI

### CY8C21X34 Qualification Status

Product Status: Production

**Document History Page** (continued)

Document Title: CY8C21634/CY8C21534/CY8C21434/CY8C21334/CY8C21234, PSoC® Programmable System-on-Chip™ Document Number: 38-12025				
Rev.	ECN	Orig. of Change	Submission Date	Description of Change
AD	4338103	PRKU	04/15/2014	Updated <a href="#">Pin Information</a> : Updated <a href="#">CY8C21234 16-pin SOIC Pin Definitions</a> (corresponding to CY8C21234): Added Note 9 and referred the same note in the description of pin 6 and pin 8. Updated <a href="#">CY8C21334 20-pin SSOP Pin Definitions</a> (corresponding to CY8C21334): Added Note 11 and referred the same note in the description of pin 5 and pin 10. Updated <a href="#">CY8C21534 28-pin SSOP Pin Definitions</a> (corresponding to CY8C21534): Added Note 13 and referred the same note in the description of pin 9 and pin 14. Updated <a href="#">CY8C21434/CY8C21634 32-pin QFN Pin Definitions</a> (corresponding to CY8C21434/CY8C21634): Added Note 16 and referred the same note in the description of pin 7, pin 12 and pin 32. Updated <a href="#">CY8C21001 56-pin SSOP Pin Definitions</a> (corresponding to CY8C21001): Added Note 18 and referred the same note in the description of pin 17, pin 18 and pin 28. Updated <a href="#">Packaging Information</a> : Updated "Important Note" below <a href="#">Figure 18</a> . Updated <a href="#">Thermal Impedances</a> : Updated Note 43 referred in <a href="#">Table 29</a> .
AE	4531967	DCHE	10/10/2014	Added <a href="#">More Information</a> . Added <a href="#">PSoC Designer</a> .
AF	4593771	DIMA	12/11/2014	Updated <a href="#">Pin Information</a> : Updated <a href="#">CY8C21001 56-pin SSOP Pin Definitions</a> : Referred Note 18 in description of pin 1. Updated <a href="#">Packaging Information</a> : spec 51-85077 – Changed revision from *E to *F. spec 51-85079 – Changed revision from *E to *F.
AG	4670626	DCHE	02/25/2015	Updated <a href="#">Errata</a> : Replaced CY8C21234 with CY8C21X34 in all instances.
AH	5394304	DCHE	08/08/2016	Updated to new template. Completing Sunset Review.

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